



NEC Electronics Inc.

**μPD424190A/L, 42S4190A/L**  
**262,144 x 18-Bit**  
**Dynamic CMOS RAM**

T-46-23-17

## Description

The μPD424190A/L and μPD42S4190A/L are fast-page dynamic RAMs organized as 262,144 words by 18 bits and designed to operate from a single power supply.

Optional features are power supply voltage (+5 V or +3.3 V) and a new refresh mode called "self-refresh."

μPD	Options
424190A	+5 V
424190L	+3.3 V
42S4190A	+5 V; self-refresh mode
42S4190L	+3.3 V; self-refresh mode

Advanced polycide technology using stacked capacitors minimizes silicon area and provides high storage cell capacity, high performance, and high reliability. A single-transistor dynamic storage cell and CMOS circuitry throughout ensure minimum power dissipation, while an on-chip circuit internally generates the negative-voltage substrate bias—automatically and transparently.

Word writing ( $I/O_1 - I/O_{18}$ ), upper byte writing ( $I/O_1 - I/O_{18}$ ), and lower byte writing ( $I/O_1 - I/O_9$ ) are all possible using UWE and LWE. If UWE or LWE goes low during an early write cycle, all data outputs remain in high impedance. Either going low causes a byte write cycle, while bringing both low at the same time results in a word write cycle. UWE and LWE cannot be staggered within the same write cycle.

Refreshing may be accomplished by a CAS before RAS refresh cycle (CBR) that internally generates the refresh address. RAS-only refresh cycles will also refresh all memory locations.

The self-refresh mode is entered by holding RAS low for longer than 100  $\mu s$  during a CBR cycle. Detection of this long RAS time starts an internal oscillator that maintains data integrity without external clocking. The slow refresh reduces the data hold current to less than 200 microamperes. Self-refresh mode is used with microprocessors that have a "sleep mode" for low-power applications such as notebook PCs.

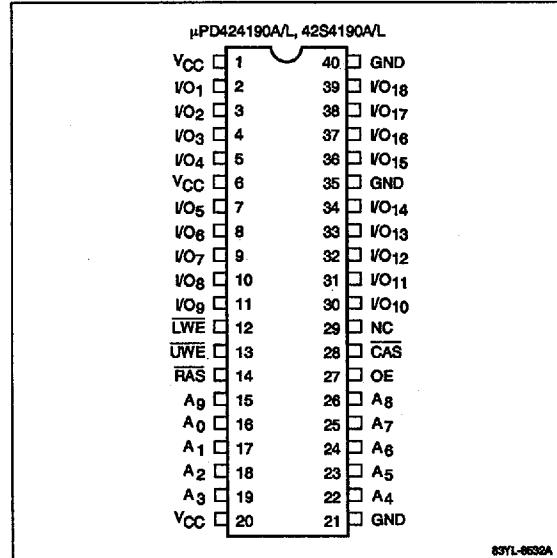
## Features

- 262,144 by 18-bit organization
- Single power supply (+5-volt or +3.3-volt)
- Self-refresh option (slow internal automatic refresh)
- Fast-page option

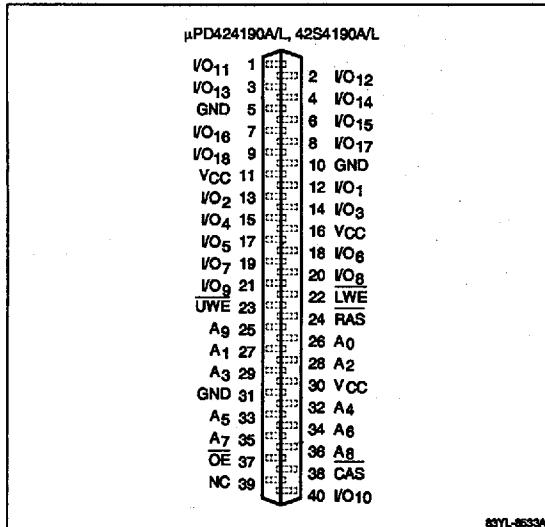
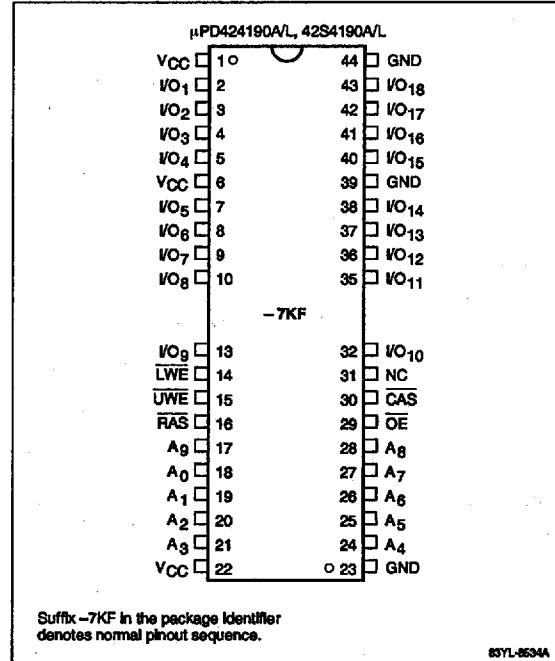
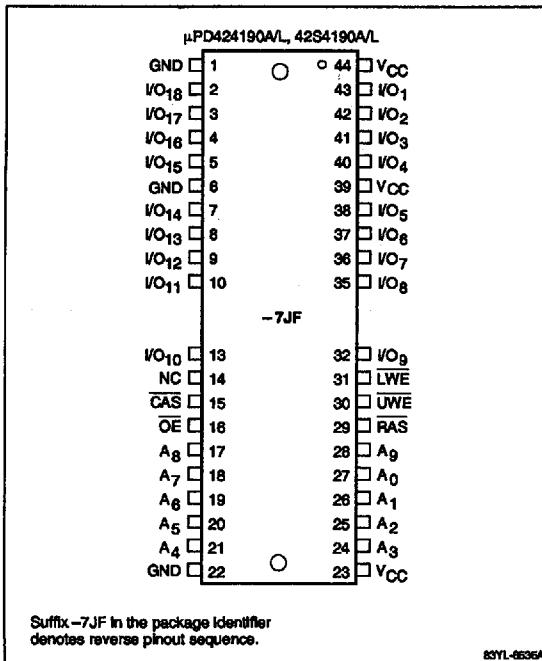
- Byte write control with UWE and LWE
- Low power dissipation
- CAS before RAS refreshing
- On-chip substrate bias generator
- TTL-compatible inputs and outputs
- Nonlatched, three-state outputs
- Low input capacitance
- Multiplexed row and column addresses
- 1024 refresh cycles every 16 ms
- 40-pin SOJ, 40-pin ZIP, and 44/40-pin TSOP plastic packaging

## Pin Configurations

### 40-Pin Plastic SOJ



83Y1-8632A

**μPD424190A/L, 42S4190A/L****Pin Configurations (cont)****40-Pin Plastic ZIP****44/40-Pin Plastic TSOP (Normal Pinouts)****44/40-Pin Plastic TSOP (Reverse Pinouts)****Pin Identification**

Name	Function
A <sub>0</sub> - A <sub>9</sub>	Address inputs
CAS	Column address strobe
VO <sub>1</sub> - VO <sub>18</sub>	Data inputs and outputs
OE	Output enable
RAS	Row address strobe
UWE and LWE	Byte write enable
GND	Ground
V <sub>CC</sub>	+5-volt or +3.3-volt power supply
NC	No connection

 **$\mu$ PD424190A/L, 42S4190A/L****Ordering Information,  $\mu$ PD424190A (+ 5-volt power)**

Part Number	RAS Access Time (max)	Fast-Page Cycle Time (max)	CAS Access Time (max)	Package
$\mu$ PD424190ALE-60	60 ns	40 ns	20 ns	40-pin plastic SOJ
LE-70	70 ns	45 ns		
LE-80	80 ns	50 ns		
$\mu$ PD424190AV-60	60 ns	40 ns	20 ns	40-pin plastic ZIP
V-70	70 ns	45 ns		
V-80	80 ns	50 ns		
$\mu$ PD424190AG5-60	60 ns	40 ns	20 ns	44/40-pin plastic TSOP (normal pinouts)
G5-70	70 ns	45 ns		
G5-80	80 ns	50 ns		
$\mu$ PD424190AG5M-60	60 ns	40 ns	20 ns	44/40-pin plastic TSOP (reverse pinouts)
G5M-70	70 ns	45 ns		
G5M-80	80 ns	50 ns		

**Ordering Information,  $\mu$ PD424190L (+ 3.3-volt power)**

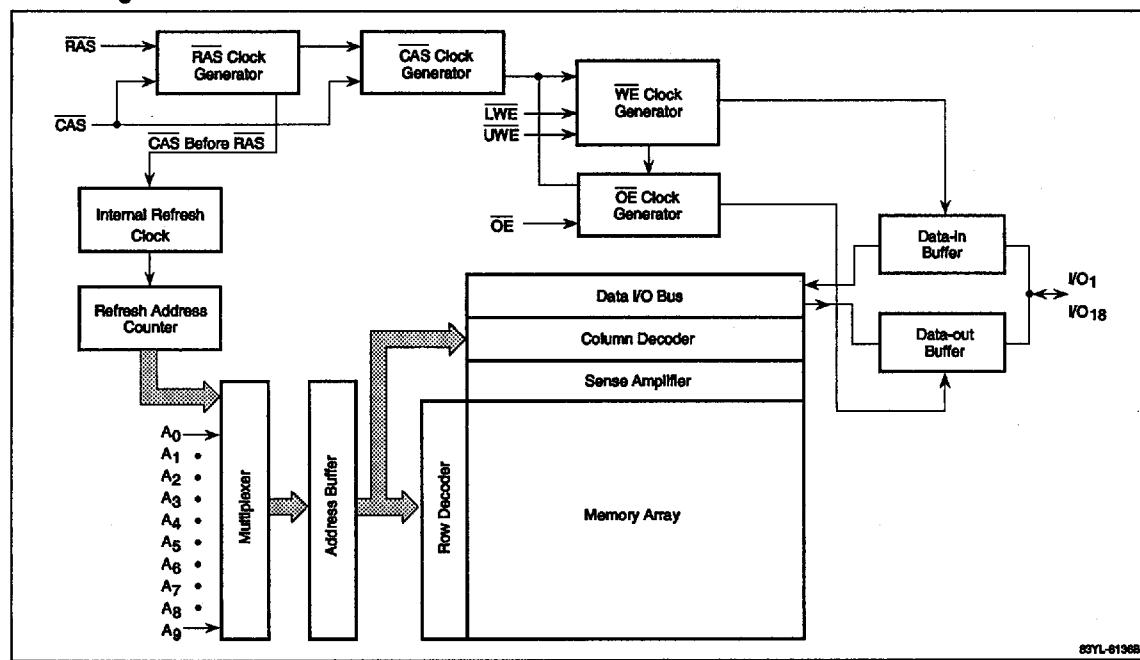
Part Number	RAS Access Time (max)	Fast-Page Cycle Time (max)	CAS Access Time (max)	Package
$\mu$ PD424190LLE-A60	60 ns	40 ns	20 ns	40-pin plastic SOJ
LE-A70	70 ns	45 ns		
LE-A80	80 ns	50 ns		
$\mu$ PD424190LV-A60	60 ns	40 ns	20 ns	40-pin plastic ZIP
V-A70	70 ns	45 ns		
V-A80	80 ns	50 ns		
$\mu$ PD424190LG5-A60	60 ns	40 ns	20 ns	44/40-pin plastic TSOP (normal pinouts)
G5-A70	70 ns	45 ns		
G5-A80	80 ns	50 ns		
$\mu$ PD424190LG5M-A60	60 ns	40 ns	20 ns	44/40-pin plastic TSOP (reverse pinouts)
G5M-A70	70 ns	45 ns		
G5M-A80	80 ns	50 ns		

***μPD424190A/L, 42S4190A/L*****NEC****Ordering Information, μPD42S4190A (+ 5-volt power; self-refresh mode)**

Part Number	RAS Access Time (max)	Fast-Page Cycle Time (max)	CAS Access Time (max)	Self-Refresh Current (max)	Package
μPD42S4190ALE-60	60 ns	40 ns	20 ns	300 μA	40-pin plastic SOJ
LE-70	70 ns	45 ns			
LE-80	80 ns	50 ns			
μPD42S4190AV-60	60 ns	40 ns	20 ns	300 μA	40-pin plastic ZIP
V-70	70 ns	45 ns			
V-80	80 ns	50 ns			
μPD42S4190AG5-60	60 ns	40 ns	20 ns	300 μA	44/40-pin plastic TSOP (normal pinouts)
G5-70	70 ns	45 ns			
G5-80	80 ns	50 ns			
μPD42S4190AG5M-60	60 ns	40 ns	20 ns	300 μA	44/40-pin plastic TSOP (reverse pinouts)
G5M-70	70 ns	45 ns			
G5M-80	80 ns	50 ns			

**Ordering Information, μPD42S4190L (+ 3.3-volt power; self-refresh mode)**

Part Number	RAS Access Time (max)	Fast-Page Cycle Time (max)	CAS Access Time (max)	Self-Refresh Current (max)	Package
μPD42S4190LLE-A60	60 ns	40 ns	20 ns	300 μA	40-pin plastic SOJ
LE-A70	70 ns	45 ns			
LE-A80	80 ns	50 ns			
μPD42S4190LV-A60	60 ns	40 ns	20 ns	300 μA	40-pin plastic ZIP
V-A70	70 ns	45 ns			
V-A80	80 ns	50 ns			
μPD42S4190LG5-A60	60 ns	40 ns	20 ns	300 μA	44/40-pin plastic TSOP (normal pinouts)
G5-A70	70 ns	45 ns			
G5-A80	80 ns	50 ns			
μPD42S4190LG5M-A60	60 ns	40 ns	20 ns	300 μA	44/40-pin plastic TSOP (reverse pinouts)
G5M-A70	70 ns	45 ns			
G5M-A80	80 ns	50 ns			

**Block Diagram**

83YL-6136B

**Truth Table**

Function	RAS	LWE	UWE	CAS	OE	I/O <sub>1</sub> - I/O <sub>9</sub>	I/O <sub>10</sub> - I/O <sub>18</sub>
Standby	V <sub>IH</sub>	X	X	X	X	High-Z	High-Z
Refresh cycle	V <sub>IL</sub>	X	X	V <sub>IH</sub>	X	High-Z	High-Z
Byte write cycle	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IH</sub>	V <sub>IL</sub>	V <sub>IH</sub>	Data input	High-Z
	V <sub>IL</sub>	V <sub>IH</sub>	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IH</sub>	High-Z	Data input
Word read cycle	V <sub>IL</sub>	V <sub>IH</sub>	V <sub>IH</sub>	V <sub>IL</sub>	V <sub>IL</sub>	Data output	Data output
Word write cycle	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IH</sub>	Data input	Data input
—	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IH</sub>	V <sub>IH</sub>	High-Z	High-Z

X = don't care.

**μPD424190A/L, 42S4190A/L****NEC****Absolute Maximum Ratings**

Voltage on any pin relative to GND

5-volt devices	-1.0 to +7.0 V
3.3-volt devices	-0.5 to +4.6 V

Operating temperature, $T_{OPR}$	0 to +70°C
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Storage temperature, $T_{STG}$	-55 to +125°C
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Short-circuit output current, $I_{OS}$	
5-volt devices	50 mA
3.3-volt devices	20 mA

Power dissipation, $P_D$	1.0 W
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Exposure to Absolute Maximum Ratings for extended periods may affect device reliability; exceeding the ratings could cause permanent damage. The device should be operated within the limits specified under DC and AC Characteristics.

**Capacitance** $T_A = 25^\circ\text{C}; f = 1 \text{ MHz}$ 

Parameter	Symbol	Max	Unit	Pins Under Test
Input capacitance	$C_{I1}$	5	pF	Addresses
	$C_{I2}$	7	pF	$\overline{WE}$ , $\overline{UE}$ , $\overline{OE}$ , RAS
Input/output capacitance	$C_O$	7	pF	$I/O_1 - I/O_{18}$

**Recommended Operating Conditions**

Parameter	Symbol	5-Volt Devices			3.3-Volt Devices			Unit
		Min	Typ	Max	Min	Typ	Max	
Input voltage, high	$V_{IH}$	2.4		$V_{CC} + 1.0$	2.0		$V_{CC} + 0.3$	V
Input voltage, low	$V_{IL}$	-1.0		0.8	-0.5		0.8	V
Supply voltage	$V_{CC}$	4.5	5.0	5.5	3.0	3.3	3.6	V
Ambient temperature	$T_A$	0		+70	0		+70	°C

**Self-Refresh Current** $T_A = 0 \text{ to } +70^\circ\text{C}; V_{CC} = +5 \text{ V } \pm 10\% \text{ (42S4190A) or } +3.3 \text{ V } \pm 0.3 \text{ V (42S4190L)}$ 

Symbol	42S4190A	42S4190L	Conditions
$I_{CC7}$	300 $\mu\text{A}$ max	100 $\mu\text{A}$ max	I/O pins: $V_{IH} \geq V_{CC} - 0.2 \text{ V}$ ; $V_{IL} \leq 0.2 \text{ V}$ or open. Other input pins: $V_{IH} \geq V_{CC} - 0.2 \text{ V}$ ; $V_{IL} \leq 0.2 \text{ V}$ or open. $t_{RAS} \geq 100 \mu\text{s}$

**DC Characteristics; 5-Volt Devices** $T_A = 0 \text{ to } +70^\circ\text{C}; V_{CC} = +5.0 \text{ V } \pm 10\%$ 

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
Standby current	$I_{CC2}$			2.0	mA	$\overline{RAS} = \overline{CAS} \geq V_{IH} \text{ (min)}$ ; $I_O = 0 \text{ mA}$
				300	$\mu\text{A}$	$\overline{RAS} = \overline{CAS} \geq V_{CC} - 0.2 \text{ V}$ ; $I_O = 0 \text{ mA}$
Input leakage current	$I_{I(L)}$	-10		10	$\mu\text{A}$	$V_{IN} = 0 \text{ V}$ to $V_{CC}$ ; all other pins not under test = 0 V
Output leakage current	$I_{O(L)}$	-10		10	$\mu\text{A}$	$D_{OUT}$ disabled; $V_{OUT} = 0 \text{ V}$ to $V_{CC}$
Output voltage, low	$V_{OL}$			0.4	V	$I_{OL} = 4.2 \text{ mA}$
Output voltage, high	$V_{OH}$	2.4			V	$I_{OH} = -5 \text{ mA}$

**DC Characteristics; 3.3-Volt Devices** $T_A = 0 \text{ to } +70^\circ\text{C}; V_{CC} = +3.3 \text{ V } \pm 0.3 \text{ V}$ 

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
Standby current	$I_{CC2}$			500	$\mu\text{A}$	$\overline{\text{RAS}} = \overline{\text{CAS}} \geq V_{IH} (\text{min}); I_O = 0 \text{ mA}$
				100	$\mu\text{A}$	$\overline{\text{RAS}} = \overline{\text{CAS}} \geq V_{CC} - 0.2 \text{ V}; I_O = 0 \text{ mA}$
Input leakage current	$I_{IL}$	-5		5	$\mu\text{A}$	$V_{IN} = 0 \text{ V to } V_{CC}$ ; all other pins not under test = 0 V
Output leakage current	$I_{OL}$	-5		5	$\mu\text{A}$	$D_{OUT}$ disabled; $V_{OUT} = 0 \text{ V to } V_{CC}$
Output voltage, low	$V_{OL}$			0.4	V	$I_{OL} = -2.0 \text{ mA}$
Output voltage, high	$V_{OH}$	2.4			V	$I_{OH} = -2.0 \text{ mA}$

**AC Characteristics** $T_A = 0 \text{ to } +70^\circ\text{C}$  $\mu\text{PD424190A}, 42\text{S4190A}; V_{CC} = +5.0 \text{ V } \pm 10\%$  $\mu\text{PD424190L}, 42\text{S4190L}; V_{CC} = +3.3 \text{ V } \pm 0.3 \text{ V}$ 

Parameter	Symbol	-60		-70		-80		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max		
Operating current, average	$I_{CC1} (+5)$	130		120		110		mA	$\overline{\text{RAS}}, \overline{\text{CAS}}$ cycling; $t_{RC} = t_{RC}$ min (Note 5)
	$I_{CC1} (+3.3)$	120		110		100			
Operating current, RAS-only refresh cycle, average	$I_{CC3} (+5)$	130		120		110		mA	$\overline{\text{RAS}}$ cycling; $\overline{\text{CAS}} \geq V_{IH}$ min; $t_{RC} = t_{RC}$ min (Note 5)
	$I_{CC3} (+3.3)$	120		110		100			
Operating current, fast-page cycle, average	$I_{CC4} (+5)$	110		100		90		mA	$\overline{\text{RAS}} \leq V_{IL}; \overline{\text{CAS}}$ cycling; $t_{PC} = t_{PC}$ min (Note 5)
	$I_{CC4} (+3.3)$	110		100		90			
Operating current, CAS before RAS refresh cycle, average	$I_{CC5} (+5)$	140		130		120		mA	$\overline{\text{RAS}}$ cycling; $\overline{\text{CAS}} \leq V_{IL}$ max; $t_{RC} = t_{RC}$ min (Note 5)
	$I_{CC5} (+3.3)$	130		120		110			
Access time from column address	$t_{AA}$		30		35		40	ns	(Notes 3, 4, 7, 8)
Access time from CAS precharge (rising edge)	$t_{ACP}$		35		40		45	ns	(Notes 3, 4, 7, 8)
Column address setup time	$t_{ASC}$	0		0		0		ns	
Row address setup time	$t_{ASR}$	0		0		0		ns	
Column address to WE delay time	$t_{AWD}$	50		55		70		ns	(Note 14)
Access time from CAS (falling edge)	$t_{CAC}$		20		20		20	ns	(Notes 3, 4, 7, 8)
Column address hold time	$t_{CAH}$	15		15		15		ns	
CAS pulse width	$t_{CAS}$	20	10,000	20	10,000	20	10,000	ns	
CAS hold time for CAS before RAS refreshing	$t_{CHR}$	15		15		15		ns	(Note 15)
CAS hold time (CBR self-refresh mode)	$t_{CHS}$	-35		-40		-50		ns	For 42S4190A/L only

**μPD424190A/L, 42S4190A/L****AC Characteristics (cont)**

Parameter	Symbol	-60		-70		-80		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max		
CAS to output in low-Z	t <sub>CLZ</sub>	0		0		0		ns	(Notes 4, 7)
Fast-page CAS precharge time	t <sub>CP</sub>	10		10		10		ns	
CAS precharge time	t <sub>CPN</sub>	10		10		10		ns	
Fast-page CAS precharge to WE delay time	t <sub>CPWD</sub>	55		60		75		ns	(Note 14)
CAS to RAS precharge time	t <sub>CRP</sub>	10		10		10		ns	(Note 10)
CAS hold time	t <sub>CSH</sub>	60		70		80		ns	
CAS setup time for CAS before RAS refresh cycle	t <sub>CSR</sub>	5		5		5		ns	(Note 15)
CAS to WE delay	t <sub>CWD</sub>	40		40		50		ns	(Note 14)
Write command referenced to CAS lead time	t <sub>CWL</sub>	15		15		15		ns	
Data-in hold time	t <sub>DH</sub>	15		15		15		ns	(Notes 13, 16)
Data-in setup time	t <sub>DS</sub>	0		0		0		ns	(Notes 13, 16)
Masked write hold time referenced to CAS	t <sub>MCH</sub>	0		0		0		ns	
Masked write setup time	t <sub>MCS</sub>	0		0		0		ns	
Masked write hold time referenced to RAS	t <sub>MRH</sub>	0		0		0		ns	
Access time from OE	t <sub>OEA</sub>		20		20		20	ns	(Notes 3, 4, 7, 8)
OE data delay time	t <sub>OED</sub>	15		15		15		ns	
OE command hold time	t <sub>OEH</sub>	0		0		0		ns	
OE to RAS inactive setup time	t <sub>OES</sub>	0		0		0		ns	
Output turnoff delay from OE	t <sub>OEZ</sub>	0	15	0	15	0	15	ns	(Note 9)
Output disable from CAS high	t <sub>OFF</sub>	0	15	0	15	0	20	ns	(Note 9)
OE to output in low-Z	t <sub>OLZ</sub>	0		0		0		ns	(Notes 5, 7)
Fast-page read or write cycle time	t <sub>PC</sub>	40		45		50		ns	(Note 6)
Fast-page read-modify-write cycle time with extended data output	t <sub>PRWC</sub>	85		90		100		ns	(Note 6)



## AC Characteristics (cont)

Parameter	Symbol	-60		-70		-80		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max		
Access time from RAS	t <sub>RAC</sub>		60		70		80	ns	(Notes 3, 4, 7, 8)
RAS to column address delay time	t <sub>RAD</sub>	15	30	15	35	15	40	ns	(Note 8)
Row address hold time	t <sub>RAH</sub>	10		10		10		ns	
Column address lead time referenced to RAS (rising edge)	t <sub>RAL</sub>	30		35		40		ns	
RAS pulse width	t <sub>RAS</sub>	60	10,000	70	10,000	80	10,000	ns	
Fast-page RAS pulse width	t <sub>RASP</sub>	60	125,000	70	125,000	80	125,000	ns	
RAS pulse width (CBR self-refresh mode)	t <sub>RASS</sub>	100		100		100		μs	For 42S4190A/L
Random read or write cycle time	t <sub>RC</sub>	120		130		150		ns	(Note 6)
RAS to CAS delay time	t <sub>RCD</sub>	20	40	20	50	20	60	ns	(Note 8)
Read command hold time referenced to CAS	t <sub>RCH</sub>	0		0		0		ns	(Note 11)
Read command setup time	t <sub>RCS</sub>	0		0		0		ns	
Refresh period	t <sub>REF</sub>		16		16		16	ms	Addresses A <sub>0</sub> - A <sub>9</sub>
RAS hold time referenced to CAS precharge	t <sub>RHCP</sub>	35		40		45		ns	
RAS precharge time	t <sub>RP</sub>	50		50		60		ns	
RAS precharge CAS hold time	t <sub>RPC</sub>	0		0		0		ns	
RAS precharge time (CBR self-refresh mode)	t <sub>RPS</sub>	120		130		150		ns	For 42S4190A/L
Read command hold time referenced to RAS	t <sub>RRH</sub>	0		0		0		ns	(Note 11)
RAS hold time	t <sub>RSH</sub>	20		20		25		ns	
Read-modify-write cycle time	t <sub>RWC</sub>	165		175		200		ns	(Note 6)
RAS to WE delay	t <sub>RWD</sub>	80		90		105		ns	(Note 14)
Write command referenced to RAS lead time	t <sub>RWL</sub>	20		20		20		ns	
Rise and fall times	t <sub>T</sub>	3	50	3	50	3	50	ns	(Note 4)
Write command hold time	t <sub>WCH</sub>	15		15		15		ns	(Note 12)

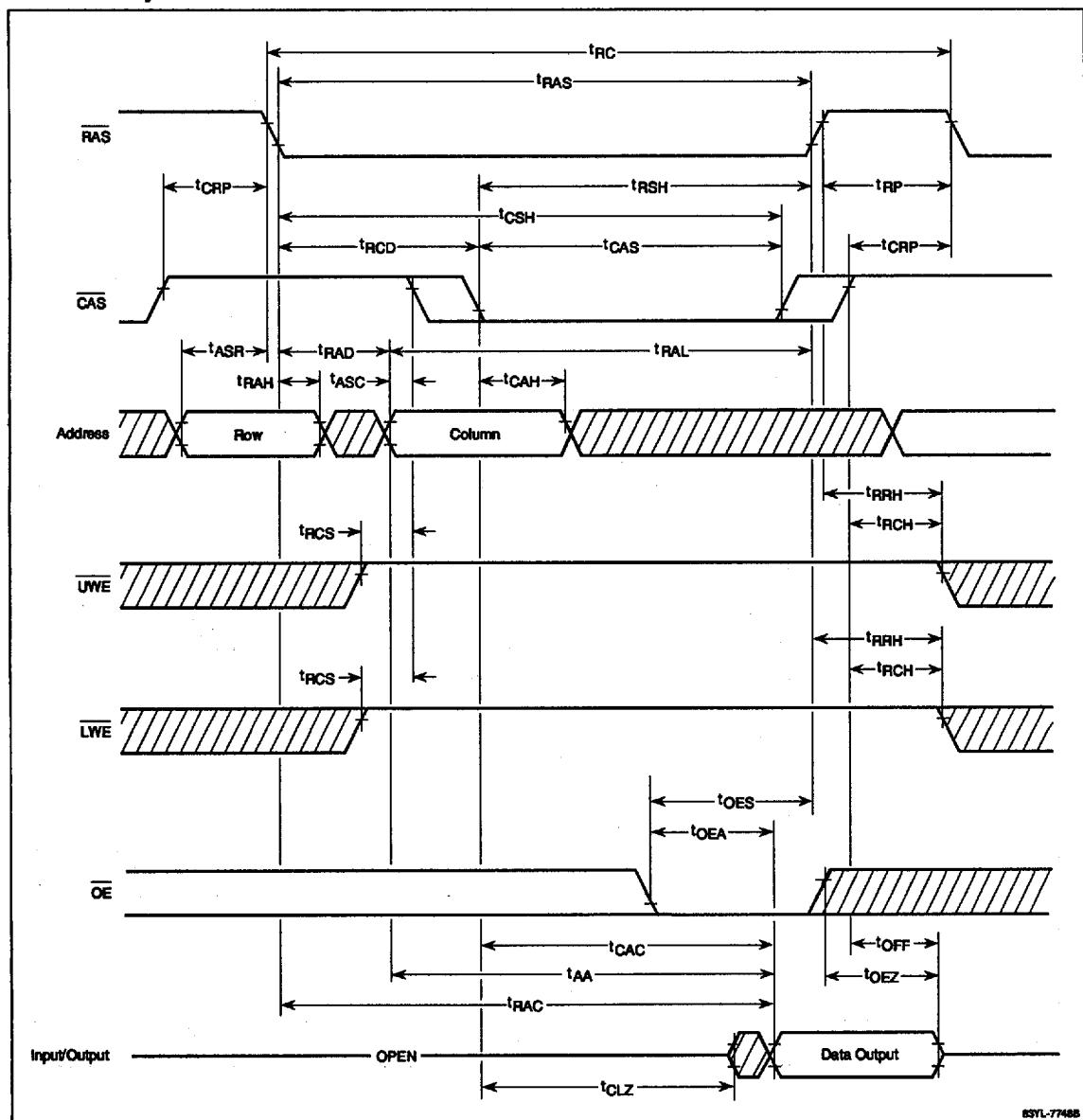
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**$\mu$ PD424190A/L, 42S4190A/L****AC Characteristics (cont)**

Parameter	Symbol	-60		-70		-80		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max		
Write command setup time	t <sub>WCS</sub>	0		0		0		ns	(Note 14)
Write command pulse width	t <sub>WP</sub>	15		15		15		ns	(Note 12)

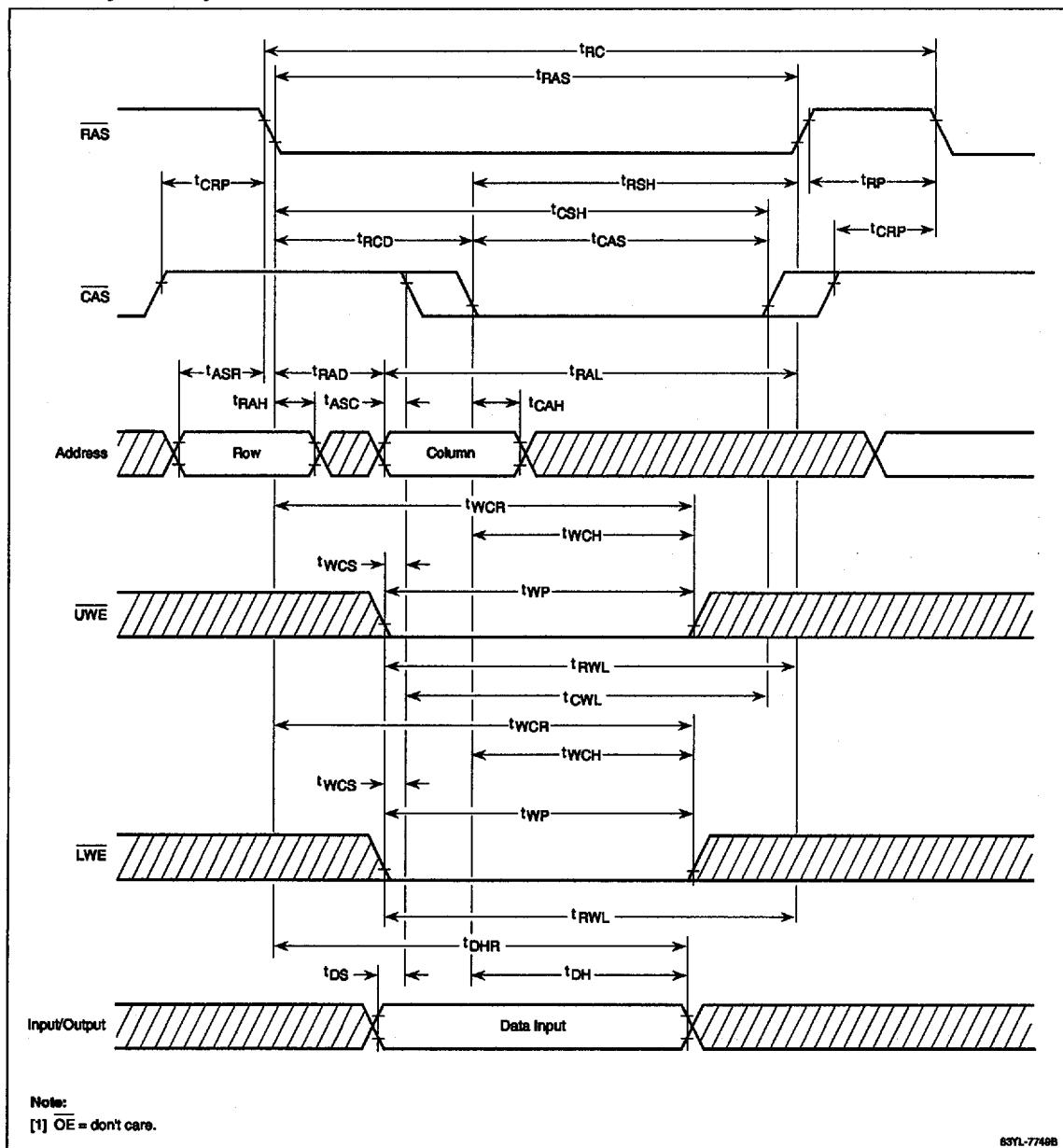
**Notes:**

- (1) All voltages are referenced to GND.
- (2) An initial pause of 100  $\mu$ s is required after power-up, followed by any eight RAS cycles, before proper device operation is achieved.
- (3) Ac measurements assume t<sub>T</sub> = 5 ns.
- (4) V<sub>IH</sub> (min) and V<sub>IL</sub> (max) are reference levels for measuring the timing of input signals. Transition times are measured between V<sub>IH</sub> and V<sub>IL</sub>.
- (5) I<sub>CC1</sub>, I<sub>CC3</sub>, I<sub>CC4</sub>, and I<sub>CC5</sub> depend on output loading and cycle rates. Specified values are obtained with the output open. I<sub>CC3</sub> is measured assuming that all column address inputs are held at either a high level or a low level during RAS-only refresh cycles. I<sub>CC4</sub> is measured assuming that all column address inputs are switched only once during each fast-page cycle.
- (6) The minimum specifications are used only to indicate the cycle time at which proper operation over the full temperature range (T<sub>A</sub> = 0 to +70°C) is assured.
- (7) Load = 2 TTL (-1 mA, +4 mA) loads and 100 pF. For 3.3-volt devices, V<sub>OH</sub> = 2.0 V and V<sub>OL</sub> = 0.8 V (ac reference levels).
- (8) If t<sub>RCD</sub> ≤ t<sub>RCD</sub> (max) and t<sub>RAD</sub> ≤ t<sub>RAD</sub> (max), access time is defined by t<sub>RAC</sub> (max).  
If t<sub>RCD</sub> ≥ t<sub>RCD</sub> (max), access time is defined by t<sub>CAC</sub> (max).  
If t<sub>RAD</sub> ≥ t<sub>RAD</sub> (max), access time is defined by t<sub>AA</sub> (max).
- (9) t<sub>OFF</sub> (max) and t<sub>OEZ</sub> (max) define the time at which the outputs become open-circuit and are not referenced to V<sub>OH</sub> or V<sub>OL</sub>.
- (10) The t<sub>CRRP</sub> requirement should be applicable for RAS/CAS cycles preceded by any cycle.
- (11) Either t<sub>RRH</sub> or t<sub>RCH</sub> must be satisfied for a read cycle.
- (12) Parameter t<sub>WP</sub> is applicable for a delayed write cycle such as a read-write/read-modify-write cycle. For early write cycles, both t<sub>WCS</sub> and t<sub>WCH</sub> must be met.
- (13) These parameters are referenced to the falling edge of CAS for early write cycles and to the falling edge of WE for delayed write or read-modify-write cycles.
- (14) t<sub>WCS</sub>, t<sub>RWD</sub>, t<sub>CWD</sub>, t<sub>CPWD</sub> and t<sub>AWD</sub> are restrictive operating parameters in read-write/read-modify-write cycles only. If t<sub>WCS</sub> ≥ t<sub>WCS</sub> (min), the cycle is an early write cycle and the data I/O pins will remain open-circuit throughout the entire cycle. If t<sub>CWD</sub> ≥ t<sub>CWD</sub> (min), t<sub>RWD</sub> ≥ t<sub>RWD</sub> (min), and t<sub>AWD</sub> ≥ t<sub>AWD</sub> (min), then the cycle is a read-write cycle and the data I/O pins will contain data read from the selected cells. If neither of the above conditions is met, the condition of the data I/O pins (at access time and until CAS returns to V<sub>IL</sub>) is indeterminate.
- (15) Holding CAS low prior to RAS going negative will initiate a CAS before RAS refresh cycle (t<sub>CSR</sub> and t<sub>CHR</sub> must be satisfied).
- (16) The first WE falling edge is used as a reference for the setup and hold requirements of t<sub>DS</sub> and t<sub>DH</sub> (late write cycle).

**NEC*****μPD424190A/L, 42S4190A/L*****Timing Waveforms****Word Read Cycle**

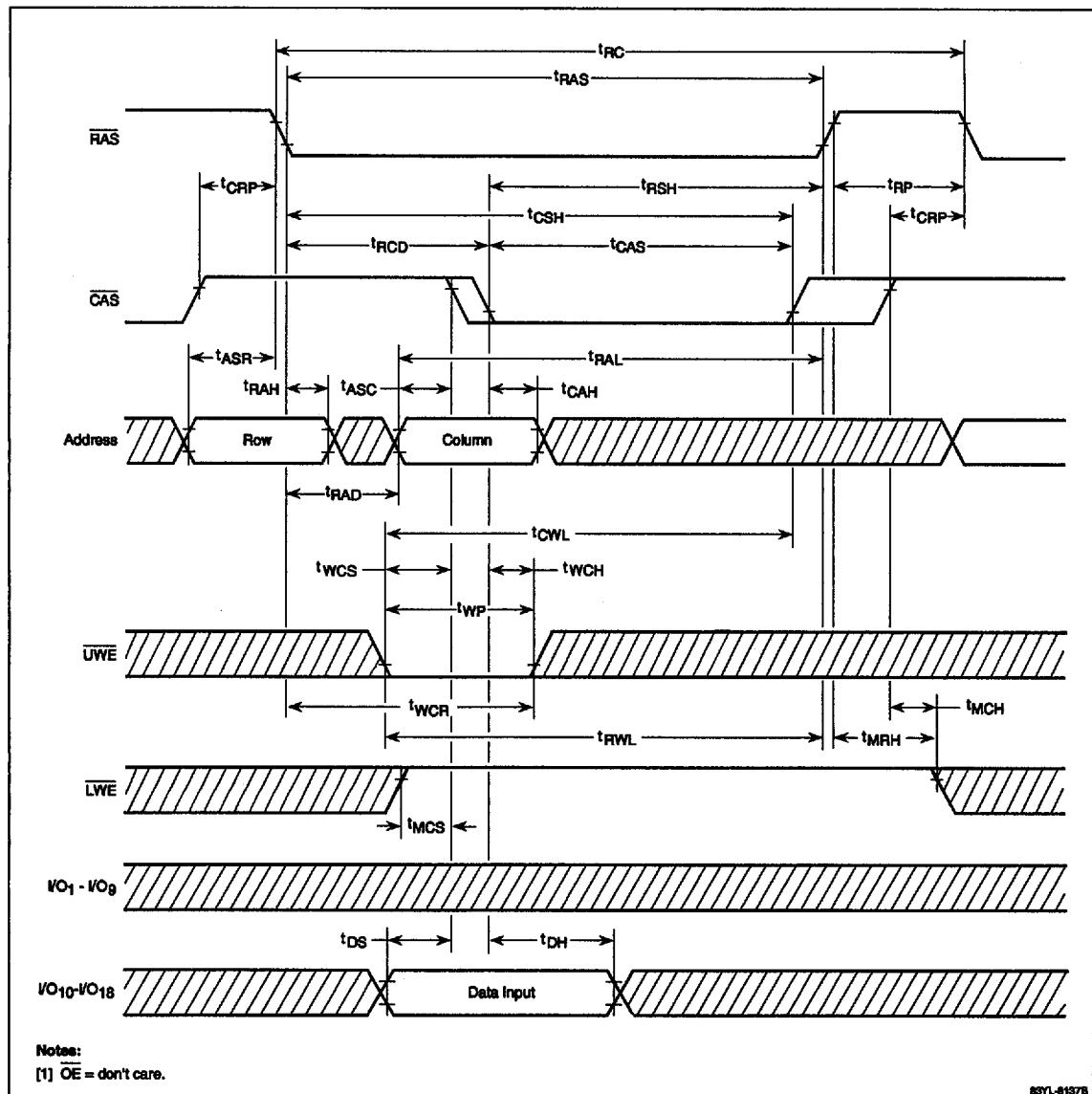
7b

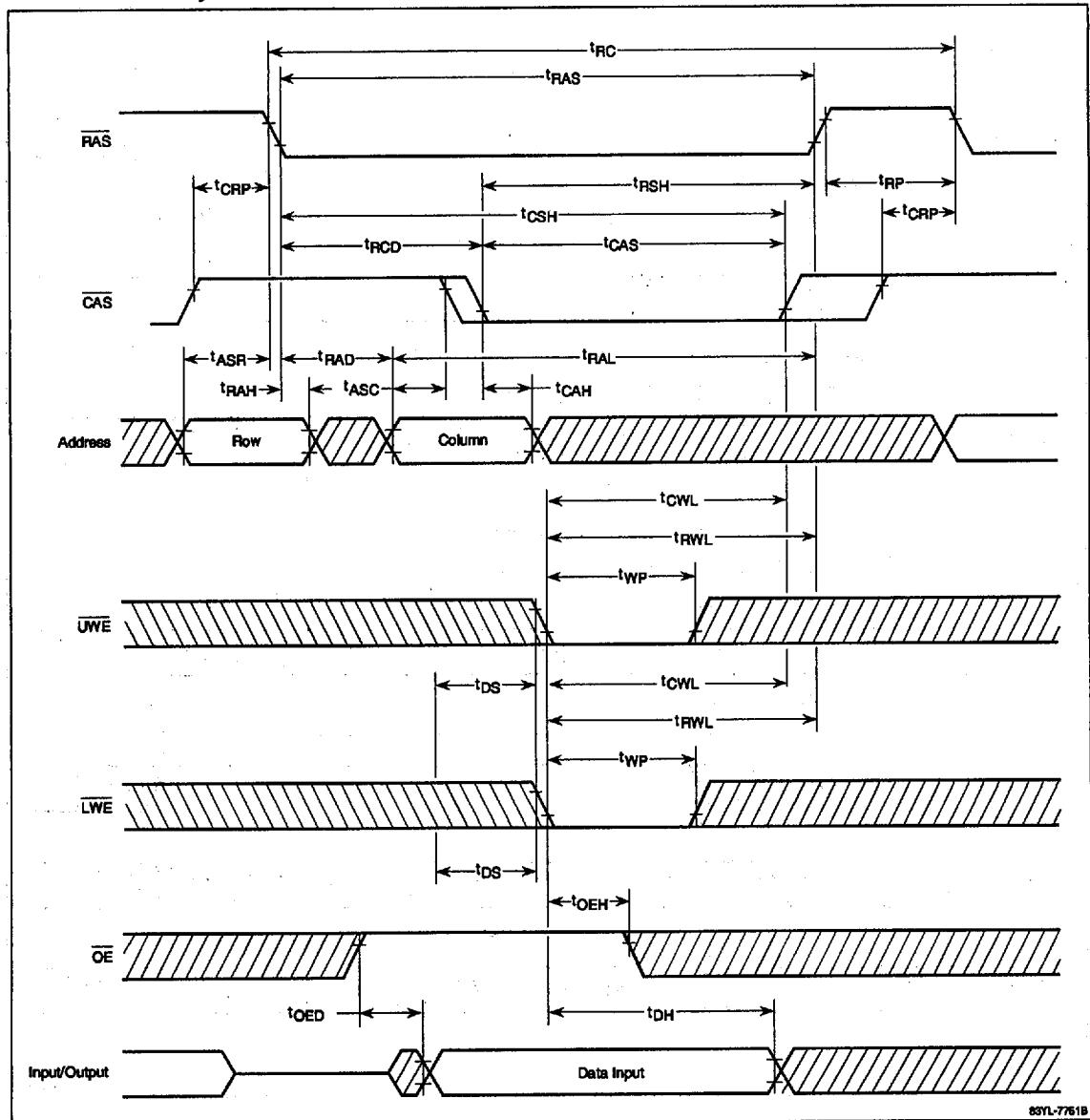
BSYL-77488

**$\mu$ PD424190A/L, 42S4190A/L****NEC****Timing Waveforms (cont)****Word Early-Write Cycle**

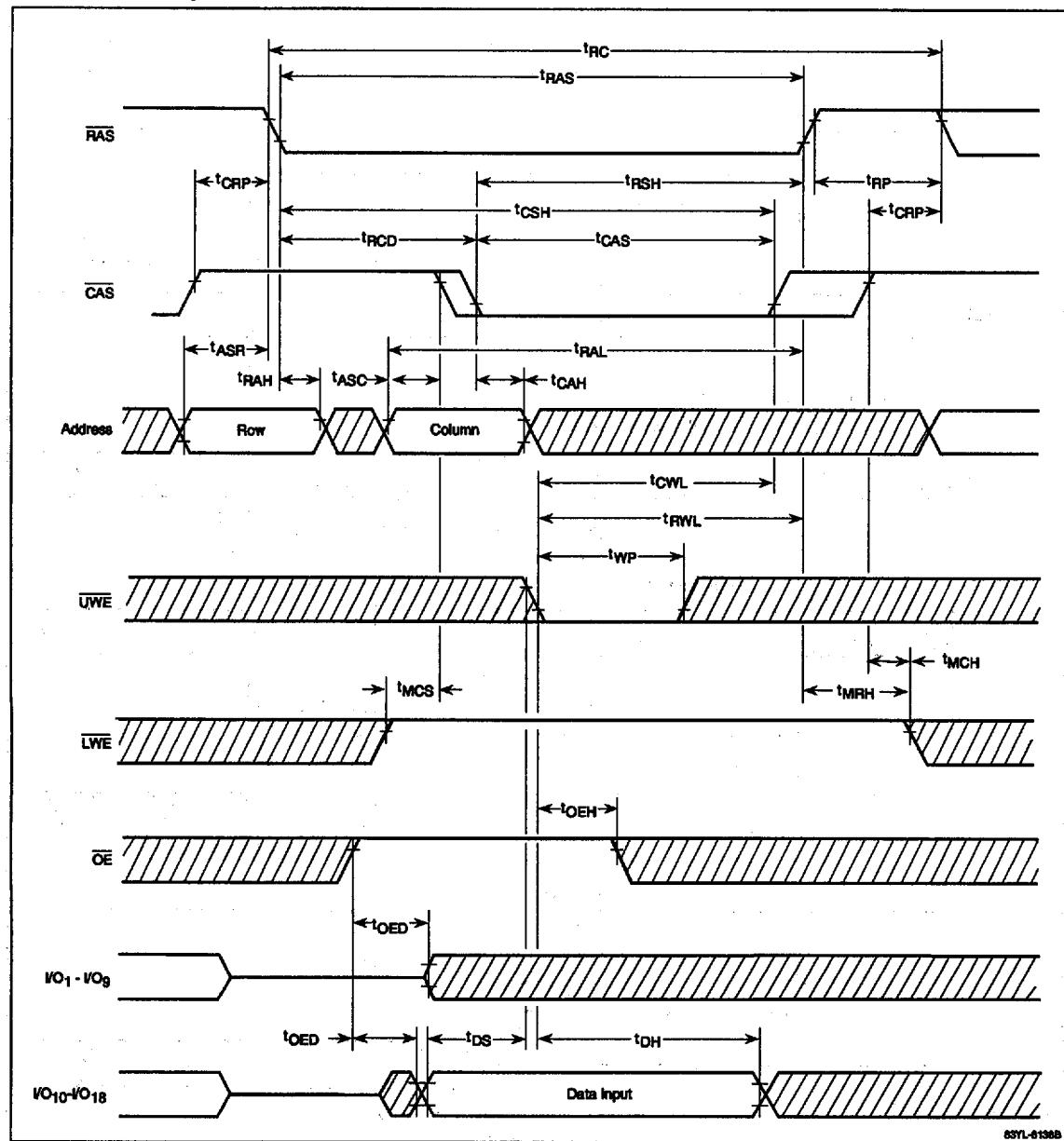
## Timing Waveforms (cont)

## Byte Early-Write Cycle



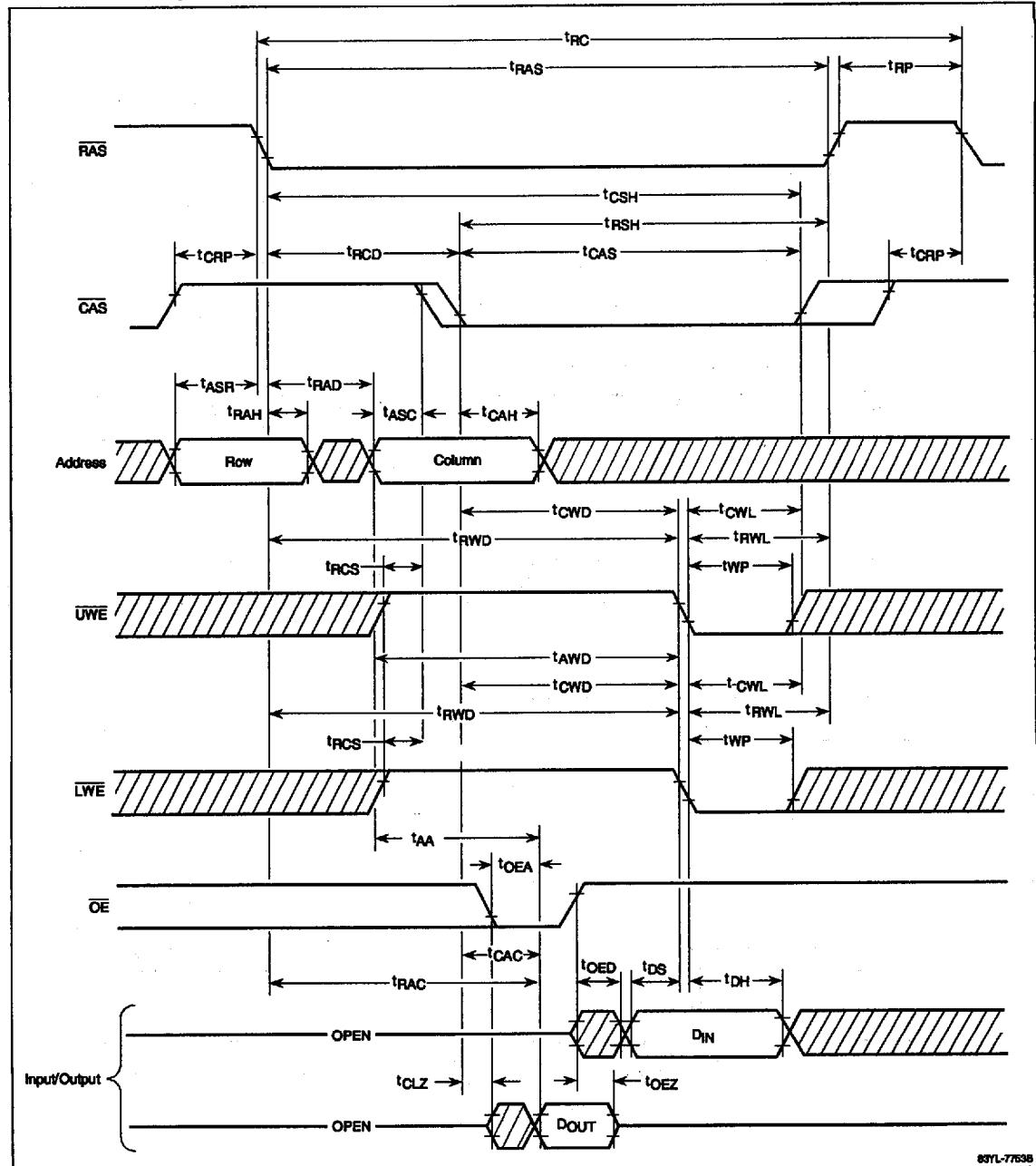
**μPD424190A/L, 42S4190A/L****NEC****Timing Waveforms (cont)****Word Late-Write Cycle**

83YL-7761B

**Timing Waveforms (cont)****Byte Late-Write Cycle**

7b

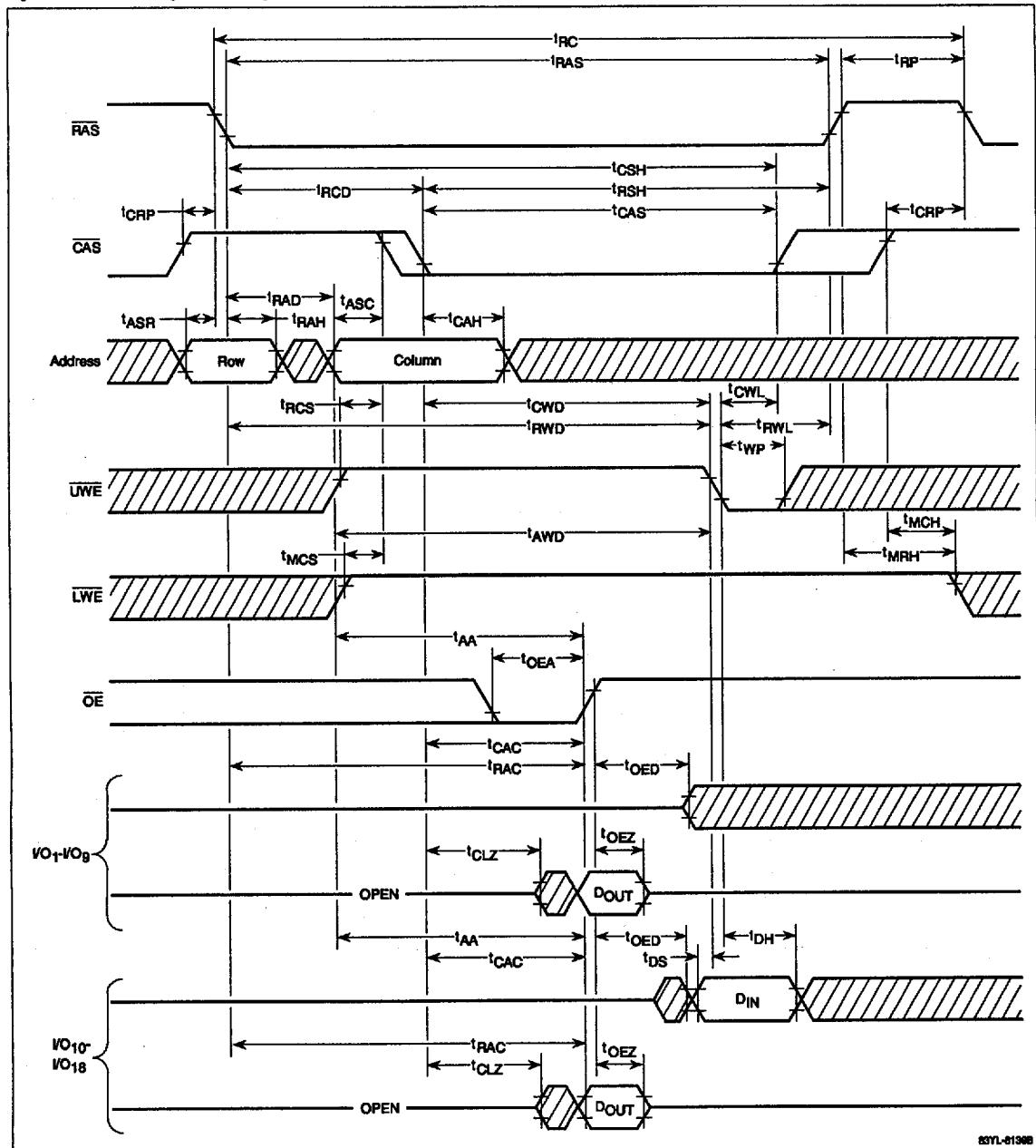
63Y1-6136B

***μPD424190A/L, 42S4190A/L*****NEC****Timing Waveforms (cont)****Word Read-Modify-Write Cycle**

83YL-7753B

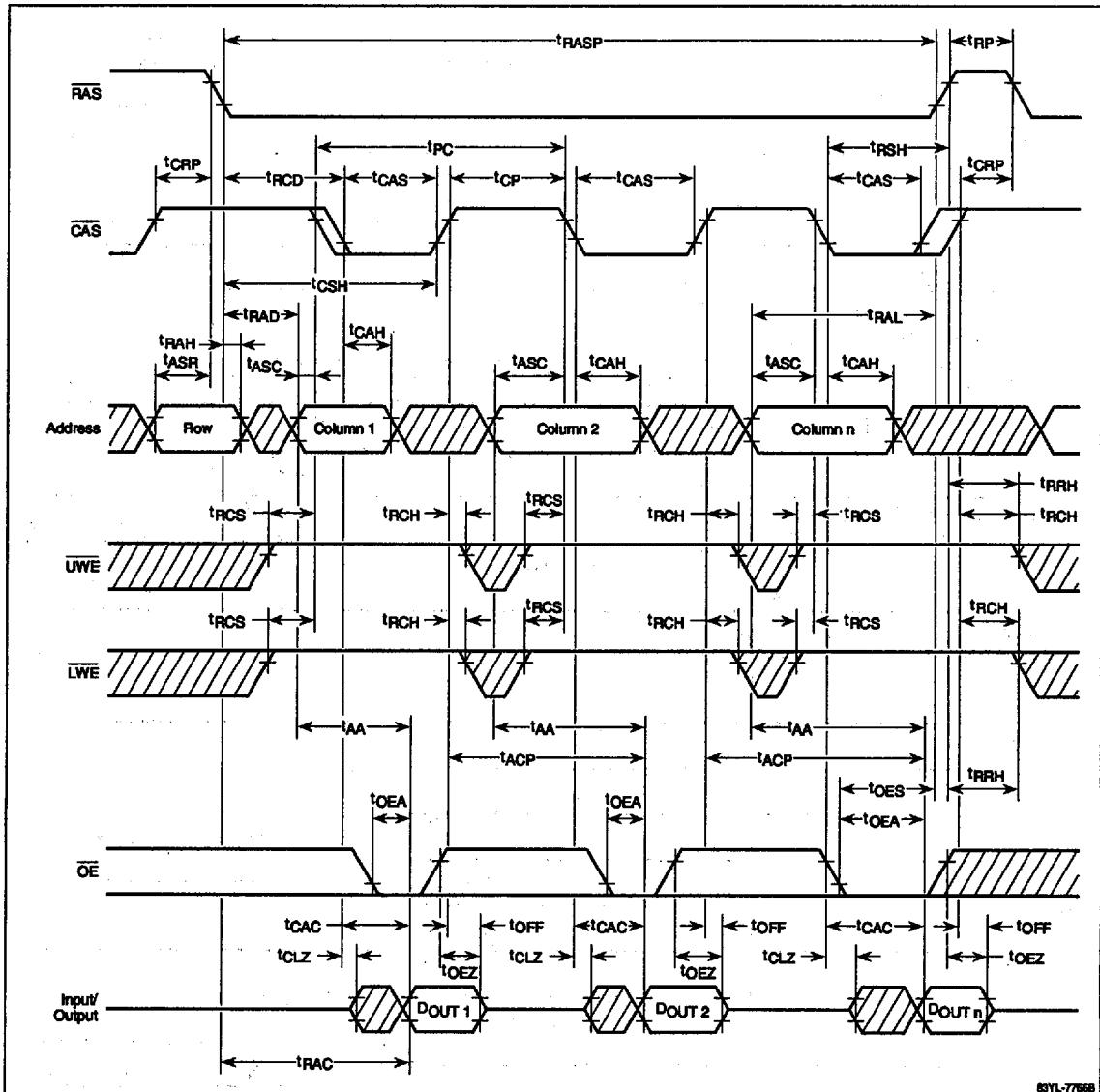
## Timing Waveforms (cont)

## Byte Read-Modify-Write Cycle

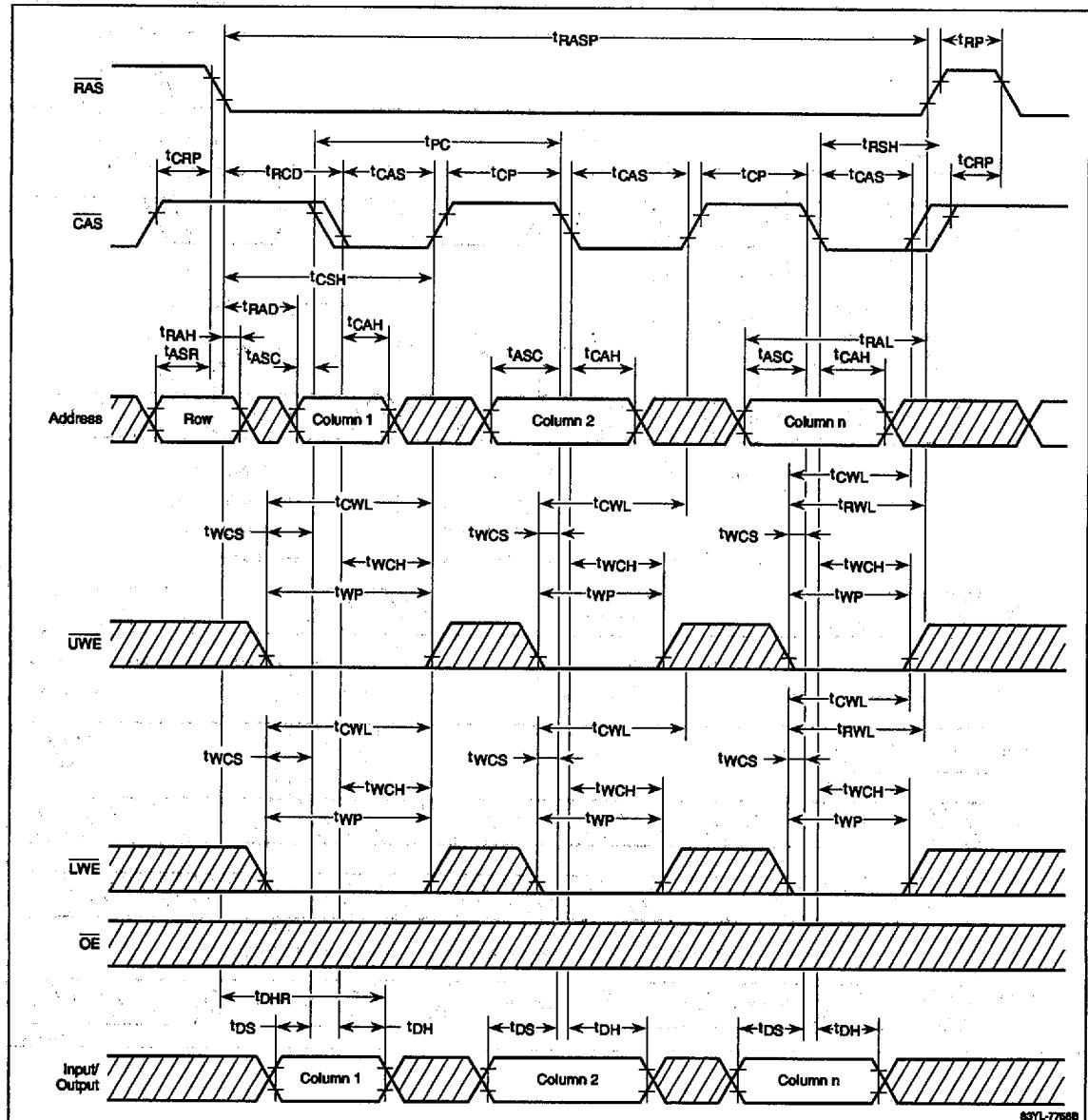


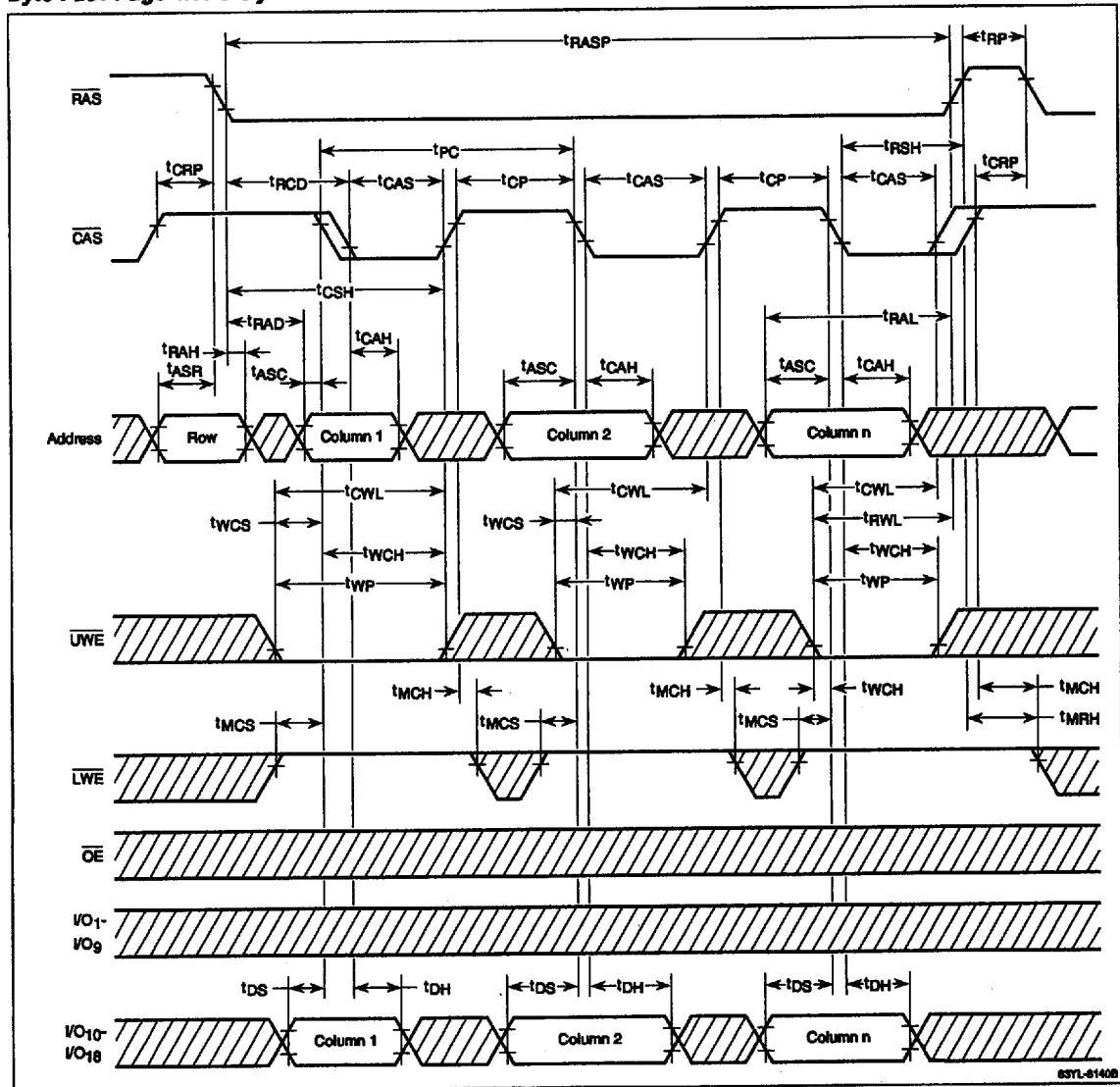
7b

83YL-6130B

**$\mu$ PD424190A/L, 42S4190A/L****NEC****Timing Waveforms (cont)****Fast-Page Read Cycle**

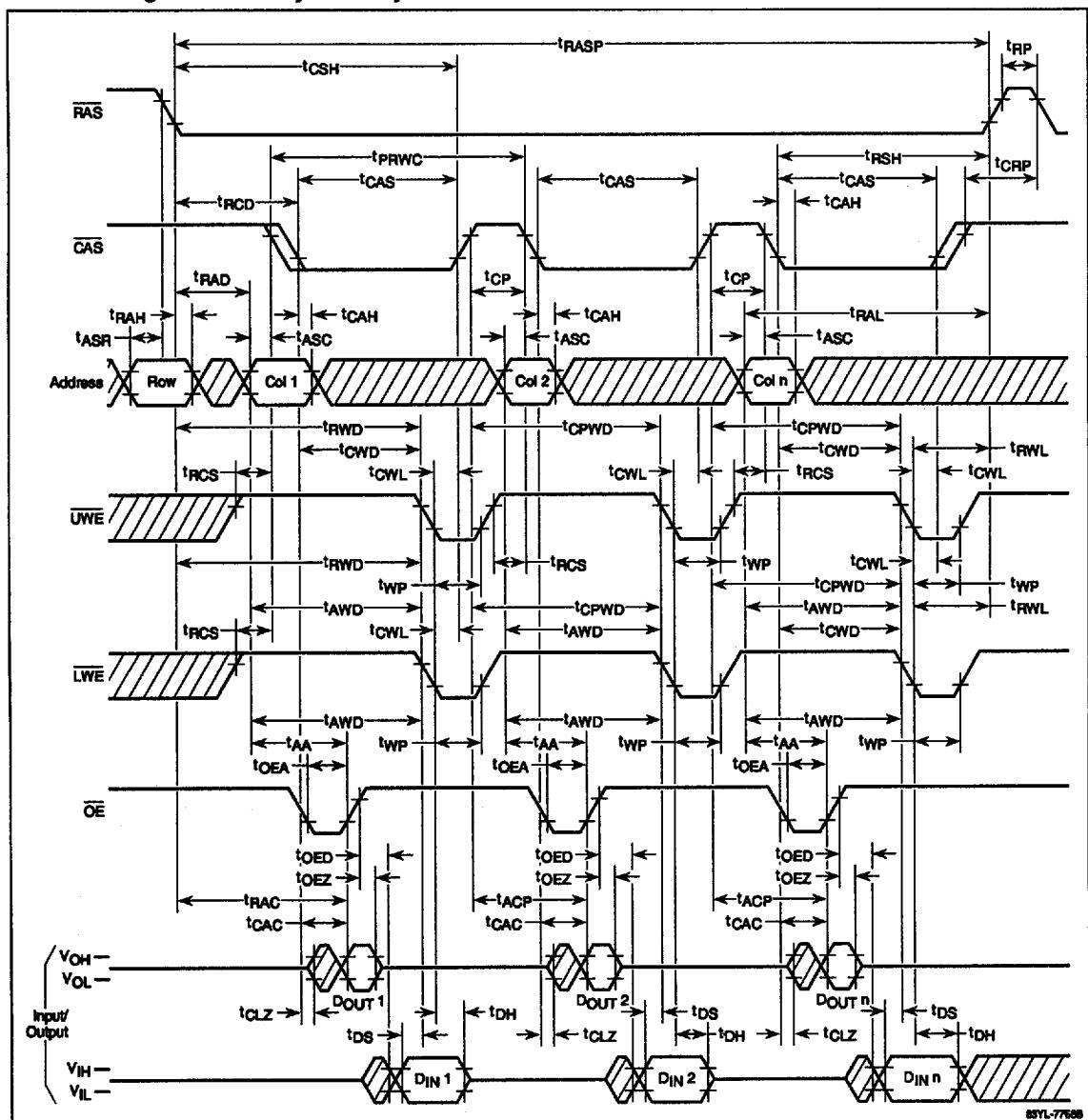
6SYL-77668

**NEC** **$\mu$ PD424190A/L, 42S4190A/L****Timing Waveforms (cont)****Word Fast-Page-Write Cycle**

***μPD424190A/L, 42S4190A/L*****Timing Waveforms (cont)****Byte Fast-Page Write Cycle**

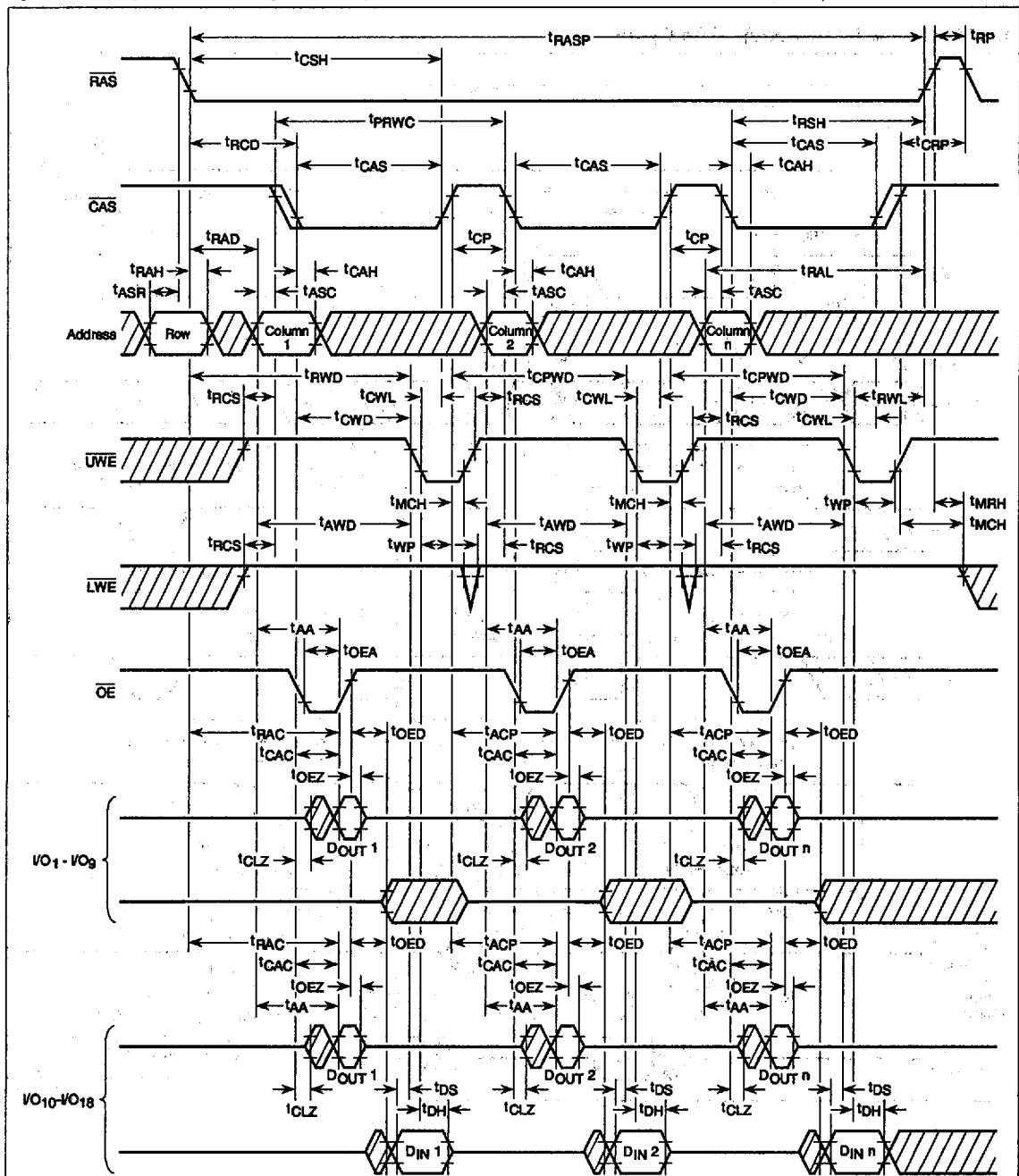
## Timing Waveforms (cont)

## Word Fast-Page Read-Modify-Write Cycle



7b

6SYL-77568

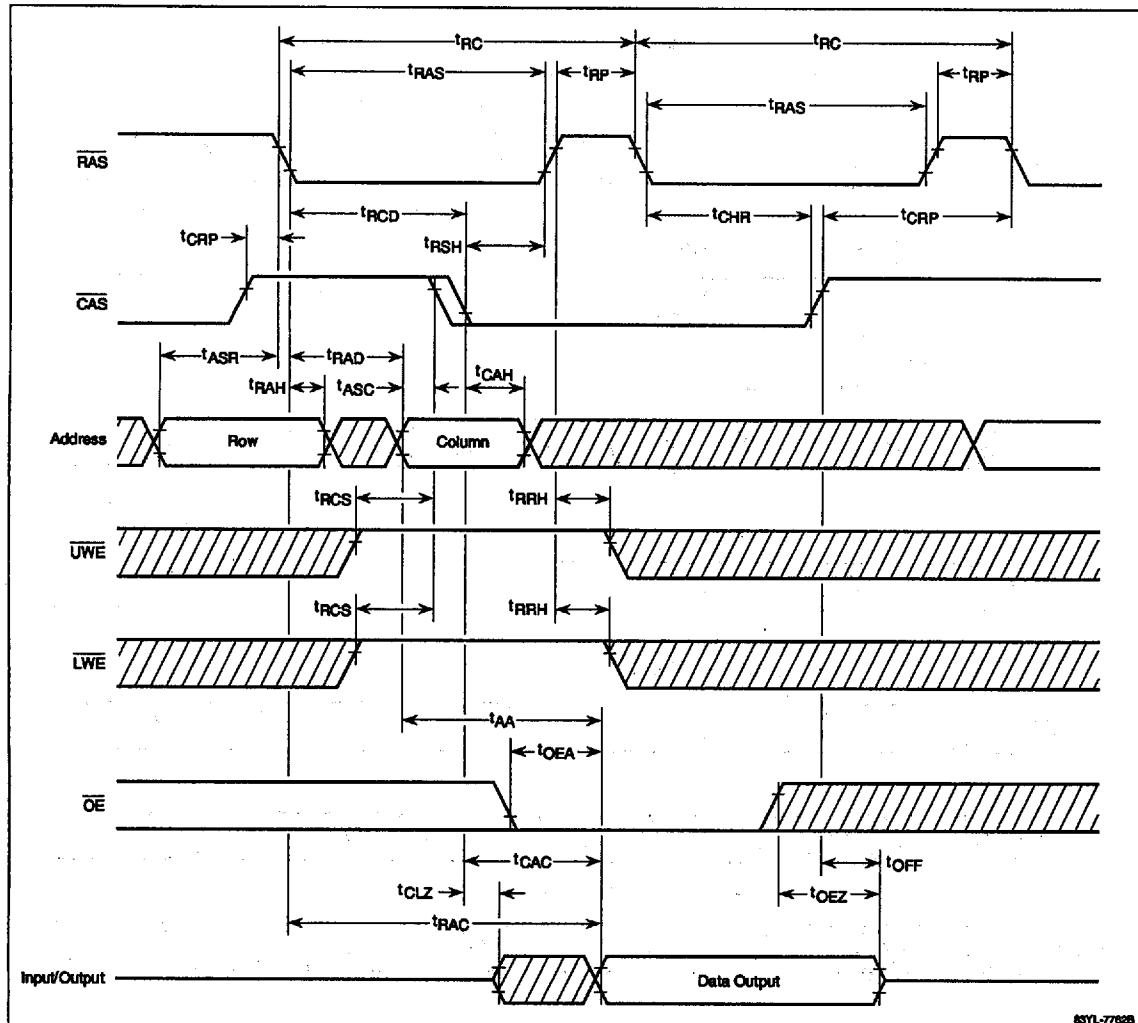
**Byte Fast-Page Read-Modify-Write Cycle**

Notes:

[1] WE = LWE or UWE for lower byte write and upper byte write cycles, respectively.

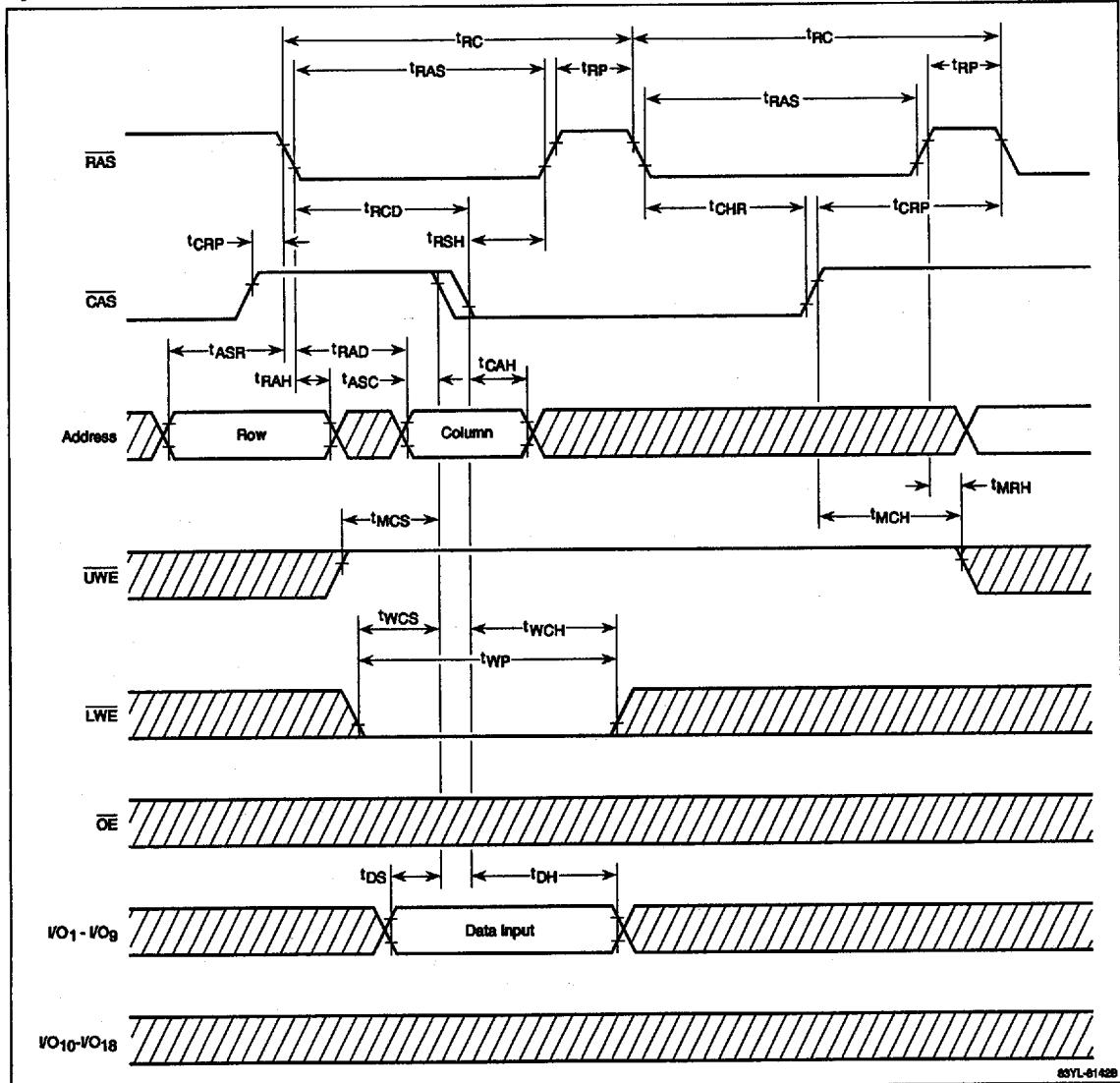
ESYL-6141B

## Timing Waveforms (cont)

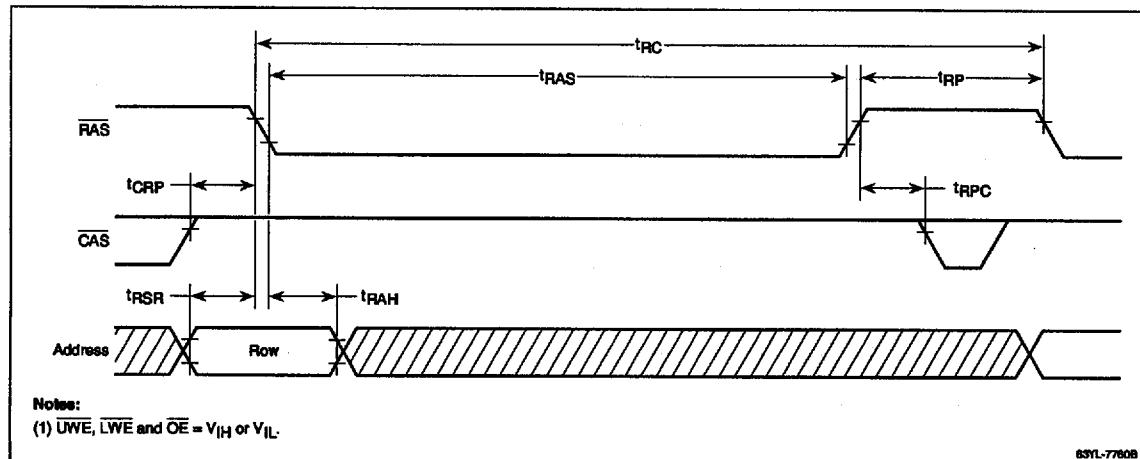
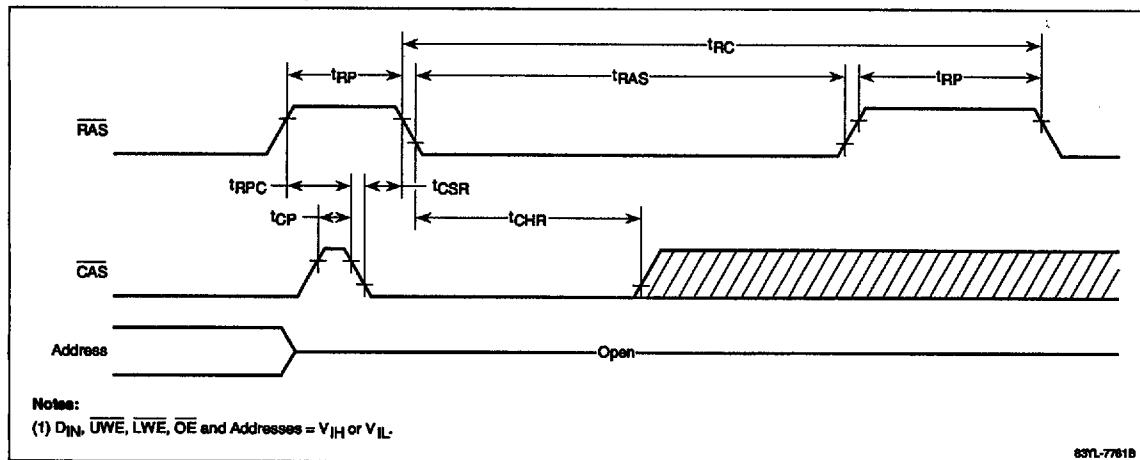
**Hidden Refresh Cycle (Read Cycle)**

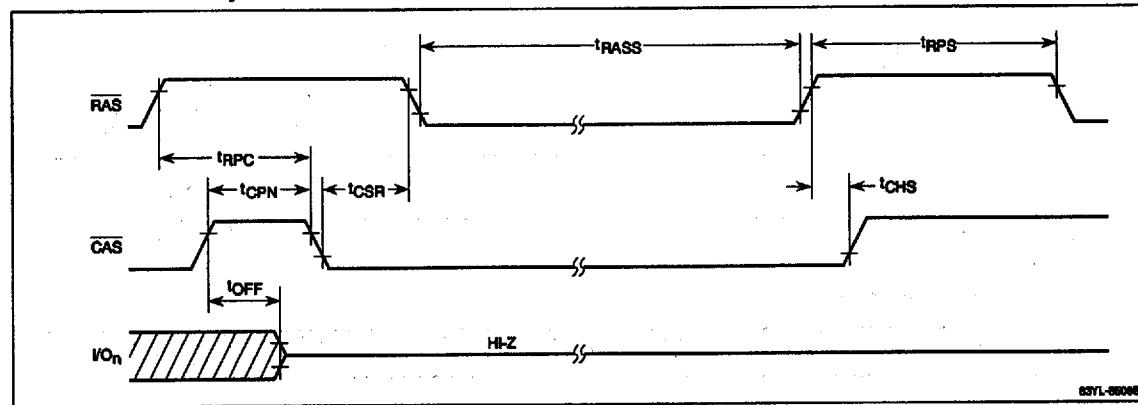
6SYL-7762B

7b

**Timing Waveforms (cont)****Byte Hidden-Refresh Cycle (Write)**

63YL-6142B

**Timing Waveforms (cont)****RAS Refresh Cycle****CAS Before RAS Refresh Cycle**

**$\mu$ PD424190A/L, 42S4190A/L****NEC****Timing Waveforms (cont)****CBR Self-Refresh Cycle**

ESYL-85046